



PATENT  
8038-1011-2

**IN THE U.S. PATENT AND TRADEMARK OFFICE**

In re application of

Koichi OHTO

Conf. 4540

Application No. 10/622,645

Group 2813

Filed July 21, 2003

Examiner E. Kielin

METHOD FOR FORMING A CAPPING LAYER  
ON A COPPER INTERCONNECT

**AMENDMENT**

Assistant Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

April 6, 2005

Sir:

In response to the Official Action mailed December 6, 2004, please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks** begin on page 4 of this paper.